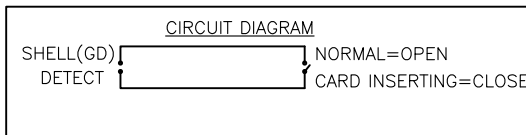
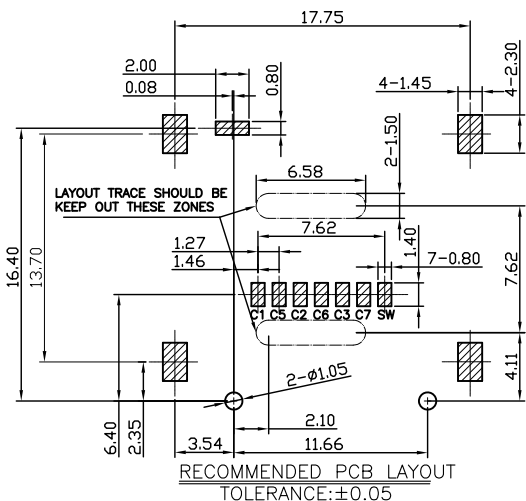


MICRO SIM CARD



CIRCUIT DIAGRAM

NOTES:

1.MATERIAL:

- 1.1 Housing: High Temperature Thermoplastic UL94V-0, Color: Black
- 1.2 Terminal: Copper Alloy
- 1.3 Shell: Stainless Steel
- 1.4 Lever: Stainless Steel
- 1.5 Cam: Stainless Steel

2.FINISH:

- 2.1 Terminal: Gold flash plating on contact area, Gold flash plating on the solder tails.
- 2.2 Shell: Gold flash plating on the solder tails.

3.SPECIALITY:

- 3.1 Rated Current: 0.5A
- 3.2 Rated Voltage: 30V
- 3.3 Contact Resistance: 50mΩ Max
- 3.4 Insulation Resistance: 1000MΩ Min 100V DC
- 3.5 Dielectric Withstanding Voltage: 500V AC
- 3.6 Solder Ability: 245±5°C; 5±0.5s
- 3.7 Durability: 5000 cycles
- 3.8 Operating Condition: Temperature: -40°C~+85°C; Humidity: 80%R.H Max

PIN No	DESCRIPTION
C1	VCC
C2	RST
C3	CLK
C4	RESERVED
C5	GND
C6	VPP
C7	I/O
C8	RESERVED
SW	SWITCH



深圳市华宇创精密电子有限公司

TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X' ±2' X.X' ±0.5'	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: MICRO SIM 1.5H(带卡勾)
	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO. HYCW48-SIM06-150B
UNIT: mm [inch] SCALE:1:1 SIZE: A4	APPROVED BY: 邱敏	DATE : 2014-02-23	DRAW NO: HYC-SIM13041021
			SHEET NO. 1 OF 1